

P-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY			
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)
- 100	0.038at V _{GS} = - 10 V	- 20	19 nC
	0.045 at V _{GS} = - 4.5 V		

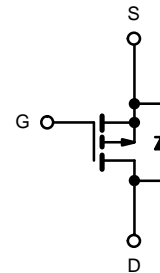
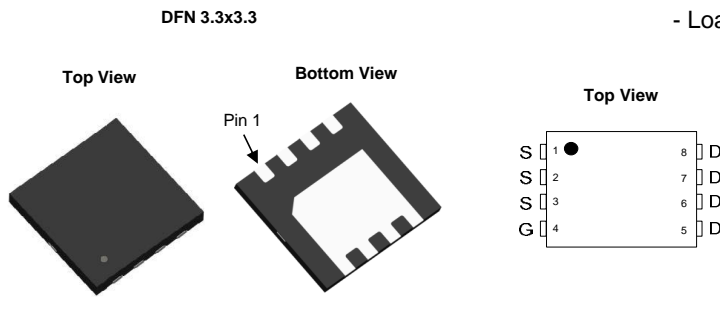
FEATURES

- DT-Trench Power MOSFET
- 100 % R_g and UIS Tested



APPLICATIONS

- Notebook
- Load Switch



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T_A = 25 °C, unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	- 100	V
Gate-Source Voltage	V _{GS}	± 20	
Continuous Drain Current (T _J = 150 °C)	I _D	T _C = 25 °C	- 20 ^a
		T _C = 70 °C	- 15 ^a
		T _A = 25 °C	- 5 ^{b, c}
		T _A = 70 °C	- 4.1 ^{b, c}
Pulsed Drain Current	I _{DM}	- 78	A
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C	
		T _A = 25 °C	- 5.5 ^{b, c}
Single Pulse Avalanche Current	I _{AS}	- 18	mJ
Single Pulse Avalanche Energy	E _{AS}	133	
Maximum Power Dissipation	P _D	T _C = 25 °C	60
		T _C = 70 °C	38.4
		T _A = 25 °C	6.3 ^{b, c}
		T _A = 70 °C	4.0 ^{b, c}
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C
Soldering Recommendations (Peak Temperature) ^{d, e}		260	

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, f}	R _{thJA}	20	45	°C/W
Maximum Junction-to-Case (Drain)	R _{thJC}	1.2	3.0	

Notes:

- Package limited.
- Surface Mounted on 1" x 1" FR4 board.
- t = 10 s.
- The DFN3x3 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.
- Maximum under Steady State conditions is 54 °C/W.

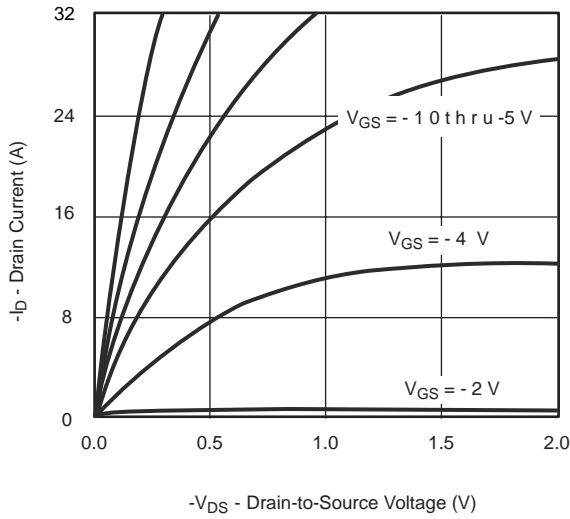
SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$	-100			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = -250\text{ }\mu\text{A}$		-31		mV/°C
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$		6.5			
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$	-1.0		-3.0	V
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -100\text{ V}, V_{GS} = 0\text{ V}$			-1	μA
		$V_{DS} = -80\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^\circ\text{C}$			-10	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} = -5\text{ V}, V_{GS} = -10\text{ V}$	-20			A
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = -10\text{ V}, I_D = -5\text{ A}$		0.038	0.050	Ω
		$V_{GS} = -4.5\text{ V}, I_D = -4\text{ A}$		0.045	0.062	
Forward Transconductance ^a	g_{fs}	$V_{DS} = -10\text{ V}, I_D = -5\text{ A}$		17		S
Dynamic^b						
Input Capacitance	C_{iss}	$V_{DS} = -50\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$		1853		pF
Output Capacitance	C_{oss}		306			
Reverse Transfer Capacitance	C_{rss}		115			
Total Gate Charge	Q_g	$V_{DS} = -50\text{ V}, V_{GS} = -10\text{ V}, I_D = -5\text{ A}$		15		nC
		$V_{DS} = -50\text{ V}, V_{GS} = -4.5\text{ V}, I_D = -4\text{ A}$		12		
Gate-Source Charge	Q_{gs}	$V_{DS} = -50\text{ V}, V_{GS} = -4.5\text{ V}, I_D = -4\text{ A}$		20		
Gate-Drain Charge	Q_{gd}		32			
Gate Resistance	R_g	$f = 1\text{ MHz}$		1.6		Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DS} = -50\text{ V}, R_L = 15\text{ }\Omega$ $I_D \cong -5\text{ A}, V_{GS} = -10\text{ V}, R_g = 1\text{ }\Omega$		17		ns
Rise Time	t_r		52			
Turn-Off Delay Time	$t_{d(off)}$		28			
Fall Time	t_f		21			
Turn-On Delay Time	$t_{d(on)}$	$V_{DS} = -50\text{ V}, R_L = 15\text{ }\Omega, I_D \cong -10\text{ A}, V_{GS} = -4.5\text{ V}, R_g = 1\text{ }\Omega$		23		
Rise Time	t_r		65			
Turn-Off Delay Time	$t_{d(off)}$		33			
Fall Time	t_f		26			
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	$T_C = 25\text{ }^\circ\text{C}$			-20	A
Pulse Diode Forward Current ^a	I_{SM}				-78	
Body Diode Voltage	V_{SD}	$I_S = -1\text{ A}$		-0.5	-1.0	V
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 5\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^\circ\text{C}$		80		ns
Body Diode Reverse Recovery Charge	Q_{rr}		135			nC
Reverse Recovery Fall Time	t_a		16			ns
Reverse Recovery Rise Time	t_b		14			

Notes:

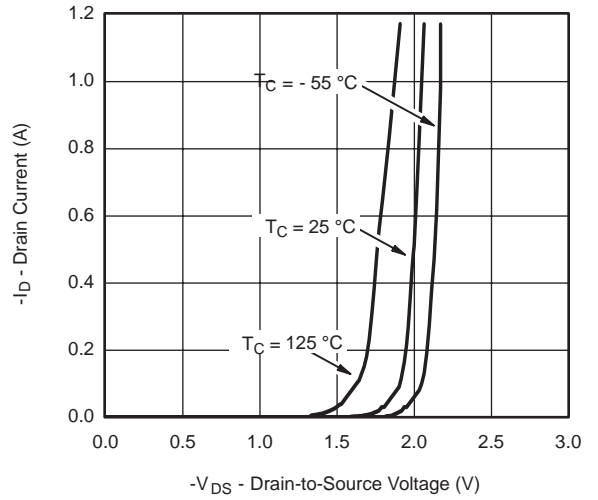
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

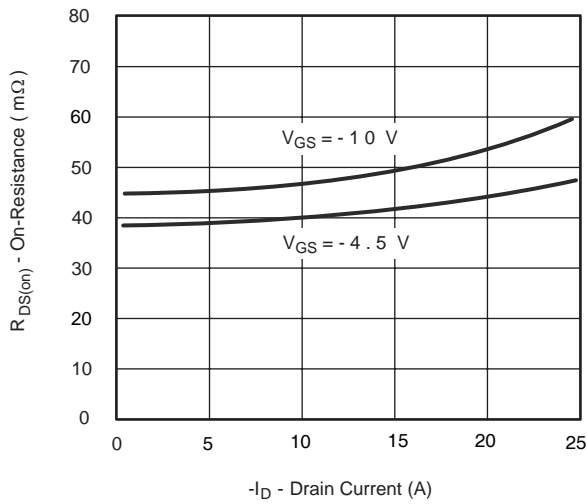
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



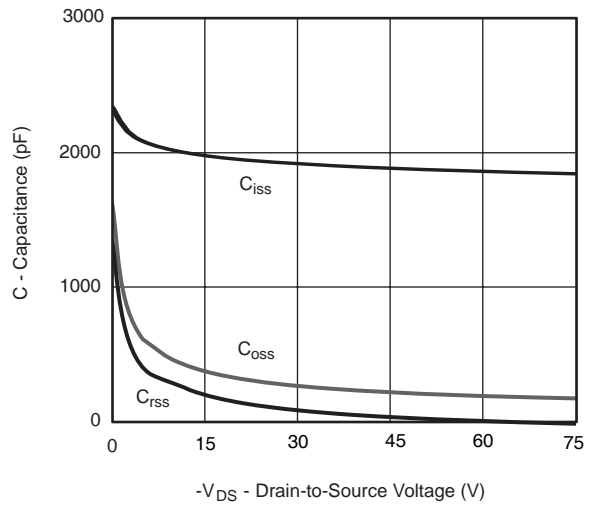
Output Characteristics



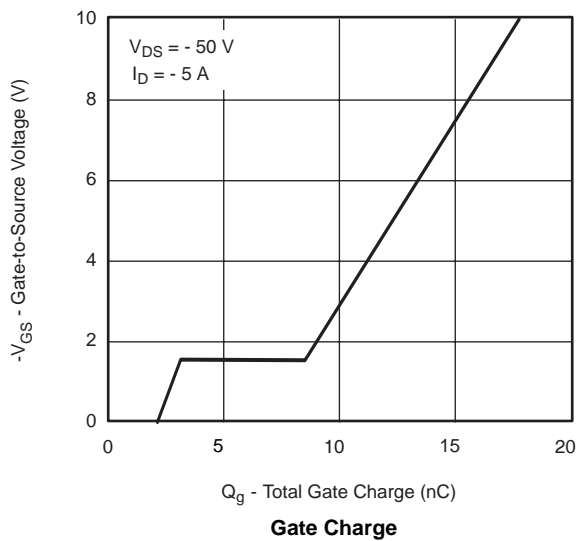
Transfer Characteristics



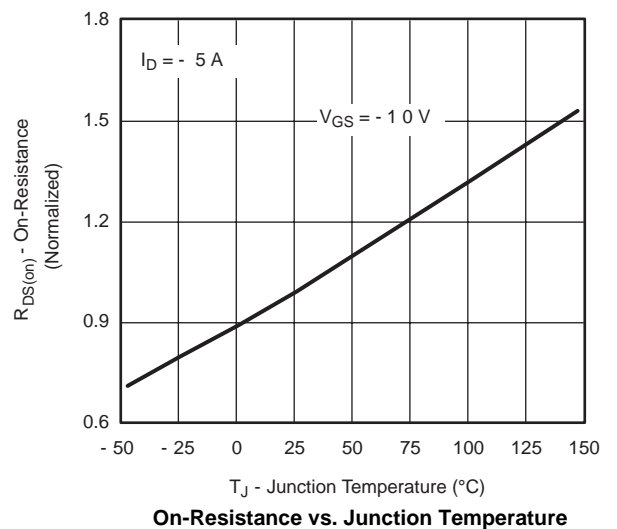
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

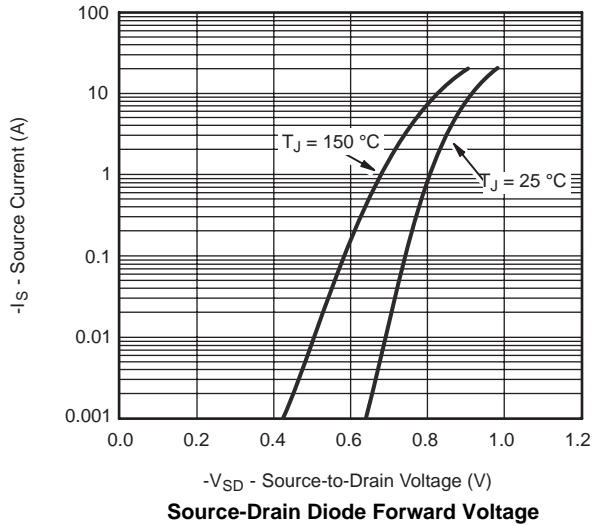


Gate Charge

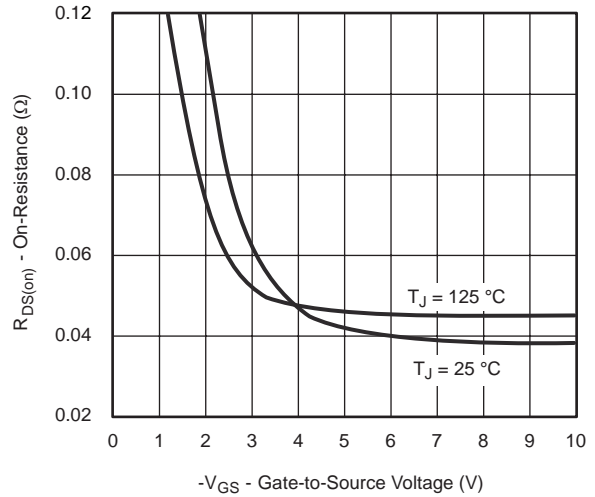


On-Resistance vs. Junction Temperature

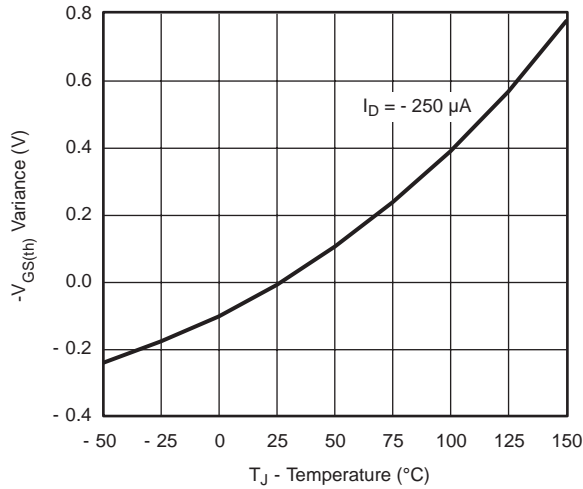
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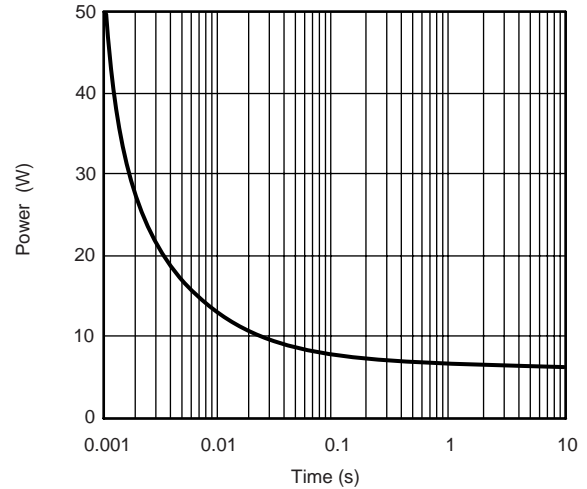
Source-Drain Diode Forward Voltage



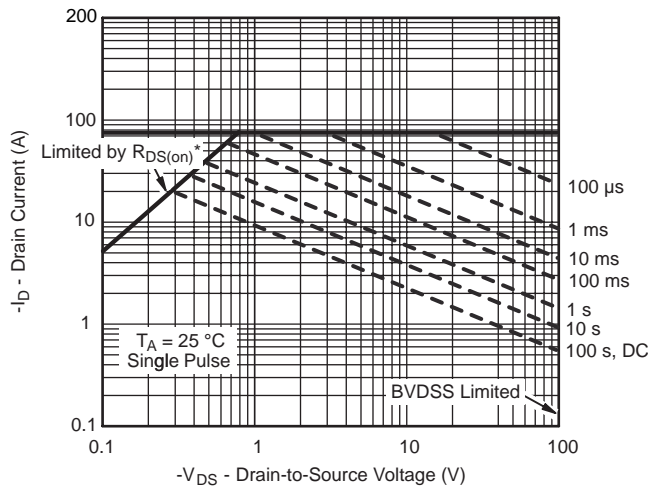
On-Resistance vs. Gate-to-Source Voltage



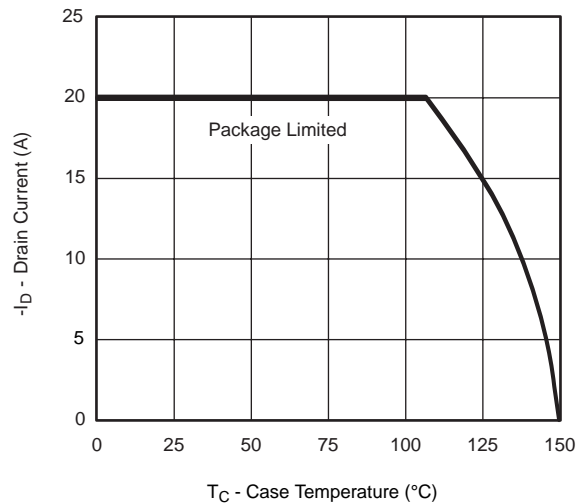
Threshold Voltage



Single Pulse Power, Junction-to-Ambient

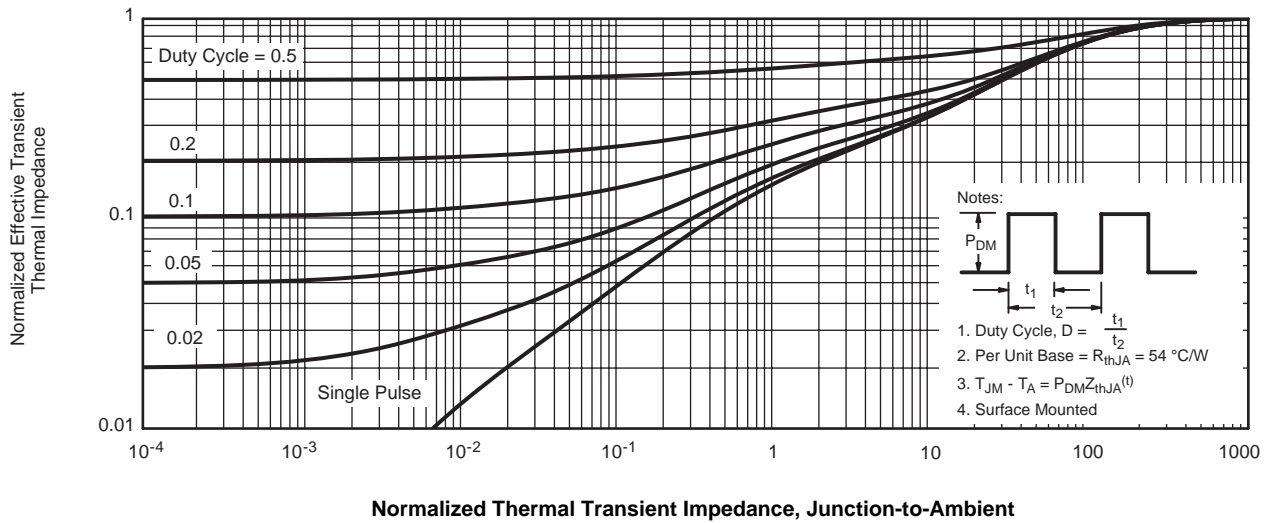


Safe Operating Area, Junction-to-Ambient



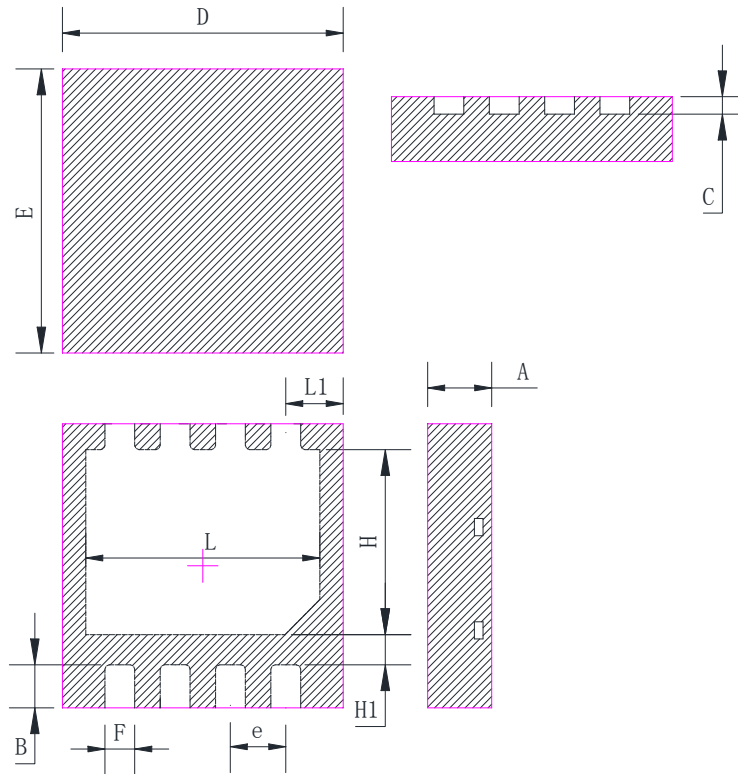
Current Derating*

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on T_{J(max)} = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

DFN3.3X3.3 PACKAGE OUTLINE DIMENSIONS



Symbol	Min	Typ	Max
A	0.70	0.75	0.80
B	0.40	0.50	0.60
C	0.153	0.203	0.253
D	3.20	3.30	3.40
E	3.20	3.30	3.40
e	0.60	0.65	0.70
F	0.30	0.35	0.40
H	2.05	2.15	2.25
H1	0.25	0.35	0.45
L	2.65	2.75	2.85
L1	0.575	0.675	0.775

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